

---

### GaAlAs Infrared Emitting Diode in $\varnothing 5$ mm (T-1 $\frac{3}{4}$ ) Package

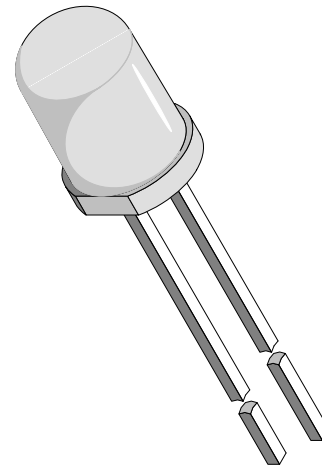
---

#### Description

The TSHA 650. series are high efficiency infrared emitting diodes in GaAlAs on GaAlAs technology, molded in a clear, untinted plastic package.

In comparison with the standard GaAs on GaAs technology these high intensity emitters feature about 70 % radiant power improvement.

In contrast to the TSHA550. series lead stand-offs are omitted.



94 8389

#### Features

- Extra high radiant power
- Suitable for DC and high pulse current operation
- Standard T-1 $\frac{3}{4}$  ( $\varnothing 5$  mm) package
- Leads formed without stand-off
- Angle of half intensity  $\varphi = \pm 24^\circ$
- Peak wavelength  $\lambda_p = 875$  nm
- High reliability
- Good spectral matching to Si photodetectors

#### Applications

Infrared remote control and free air transmission systems with high power and comfortable radiation angle requirements in combination with PIN photodiodes or phototransistors.

Because of the reduced radiance absorption in glass at the wavelength of 875 nm, this emitter series is also suitable for systems with panes in the transmission range between emitter and detector.

### Absolute Maximum Ratings

 $T_{amb} = 25^{\circ}\text{C}$ 

Parameter	Test Conditions	Symbol	Value	Unit
Reverse Voltage		$V_R$	5	V
Forward Current		$I_F$	100	mA
Peak Forward Current	$t_p/T=0.5, t_p=100\ \mu\text{s}$	$I_{FM}$	200	mA
Surge Forward Current	$t_p=100\ \mu\text{s}$	$I_{FSM}$	2.5	A
Power Dissipation		$P_V$	210	mW
Junction Temperature		$T_j$	100	$^{\circ}\text{C}$
Operating Temperature Range		$T_{amb}$	-55...+100	$^{\circ}\text{C}$
Storage Temperature Range		$T_{stg}$	-55...+100	$^{\circ}\text{C}$
Soldering Temperature	$t \leq 5\text{sec}, 2\ \text{mm from case}$	$T_{sd}$	260	$^{\circ}\text{C}$
Thermal Resistance Junction/Ambient		$R_{thJA}$	350	K/W

### Basic Characteristics

 $T_{amb} = 25^{\circ}\text{C}$ 

Parameter	Test Conditions	Symbol	Min	Typ	Max	Unit
Forward Voltage	$I_F = 100\ \text{mA}, t_p = 20\ \text{ms}$	$V_F$		1.5	1.8	V
Temp. Coefficient of $V_F$	$I_F = 100\ \text{mA}$	$TK_{VF}$		-1.6		mV/K
Reverse Current	$V_R = 5\ \text{V}$	$I_R$			100	$\mu\text{A}$
Junction Capacitance	$V_R = 0\ \text{V}, f = 1\ \text{MHz}, E = 0$	$C_j$		20		pF
Temp. Coefficient of $\phi_e$	$I_F = 20\ \text{mA}$	$TK_{\phi_e}$		-0.7		%/K
Angle of Half Intensity		$\phi$		$\pm 24$		deg
Peak Wavelength	$I_F = 100\ \text{mA}$	$\lambda_p$		875		nm
Spectral Bandwidth	$I_F = 100\ \text{mA}$	$\Delta\lambda$		80		nm
Temp. Coefficient of $\lambda_p$	$I_F = 100\ \text{mA}$	$TK_{\lambda_p}$		0.2		nm/K
Rise Time	$I_F = 100\ \text{mA}$	$t_r$		600		ns
Rise Time	$I_F = 1.5\ \text{A}$	$t_r$		300		ns
Fall Time	$I_F = 100\ \text{mA}$	$t_f$		600		ns
Fall Time	$I_F = 1.5\ \text{A}$	$t_f$		300		ns

## Type Dedicated Characteristics

$T_{amb} = 25^{\circ}\text{C}$

Parameter	Type	Test Conditions	Symbol	Min	Typ	Max	Unit
Forward Voltage	TSHA6500/6501	$I_F=1.5\text{A}, t_p=100\mu\text{s}$	$V_F$		3.2	4.9	V
	TSHA6502/6503	$I_F=1.5\text{A}, t_p=100\mu\text{s}$	$V_F$		3.2	4.5	V
Radiant Intensity	TSHA6500	$I_F=100\text{mA}, t_p=20\text{ms}$	$I_e$	12	20		mW/sr
	TSHA6501	$I_F=100\text{mA}, t_p=20\text{ms}$	$I_e$	16	25		mW/sr
	TSHA6502	$I_F=100\text{mA}, t_p=20\text{ms}$	$I_e$	20	30		mW/sr
	TSHA6503	$I_F=100\text{mA}, t_p=20\text{ms}$	$I_e$	24	35		mW/sr
Radiant Intensity	TSHA6500	$I_F=1.5\text{A}, t_p=100\mu\text{s}$	$I_e$	150	240		mW/sr
	TSHA6501	$I_F=1.5\text{A}, t_p=100\mu\text{s}$	$I_e$	200	300		mW/sr
	TSHA6502	$I_F=1.5\text{A}, t_p=100\mu\text{s}$	$I_e$	250	360		mW/sr
	TSHA6503	$I_F=1.5\text{A}, t_p=100\mu\text{s}$	$I_e$	300	420		mW/sr
Radiant Power	TSHA6500	$I_F=100\text{mA}, t_p=20\text{ms}$	$\phi_e$		22		mW
	TSHA6501	$I_F=100\text{mA}, t_p=20\text{ms}$	$\phi_e$		23		mW
	TSHA6502	$I_F=100\text{mA}, t_p=20\text{ms}$	$\phi_e$		24		mW
	TSHA6503	$I_F=100\text{mA}, t_p=20\text{ms}$	$\phi_e$		25		mW

## Typical Characteristics ( $T_{amb} = 25^{\circ}\text{C}$ unless otherwise specified)

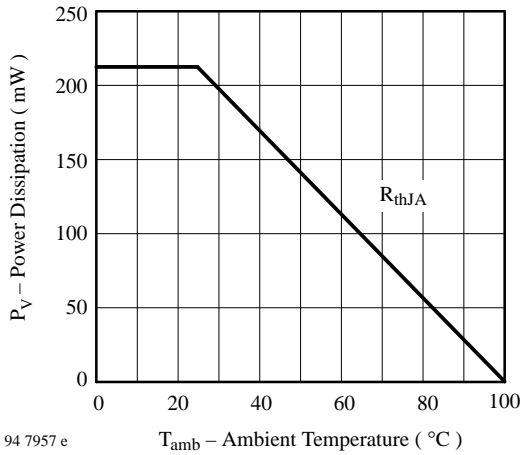


Figure 1 : Power Dissipation vs. Ambient Temperature

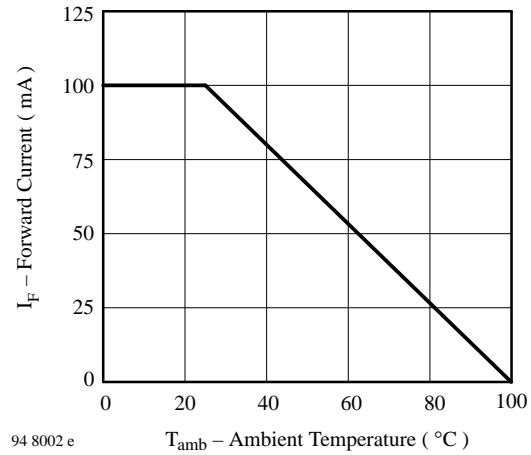


Figure 2 : Forward Current vs. Ambient Temperature

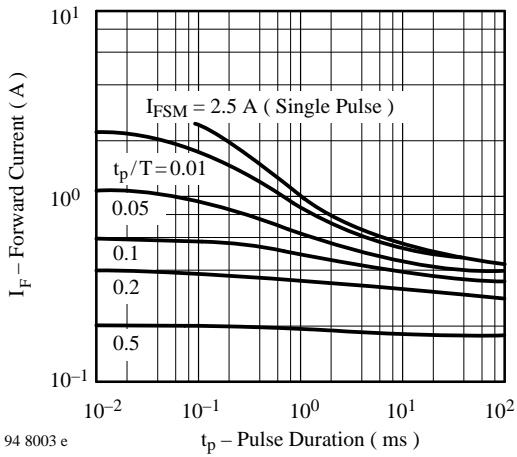


Figure 3 : Pulse Forward Current vs. Pulse Duration

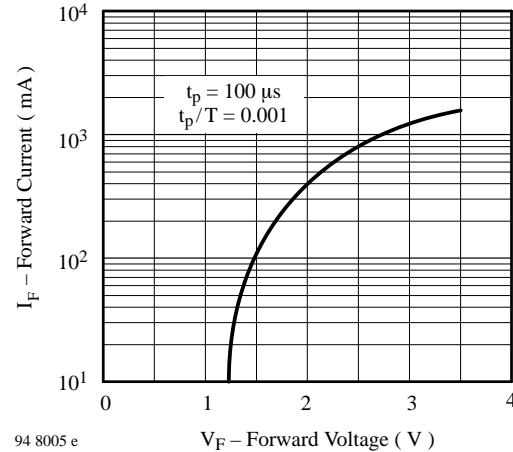


Figure 4 : Forward Current vs. Forward Voltage

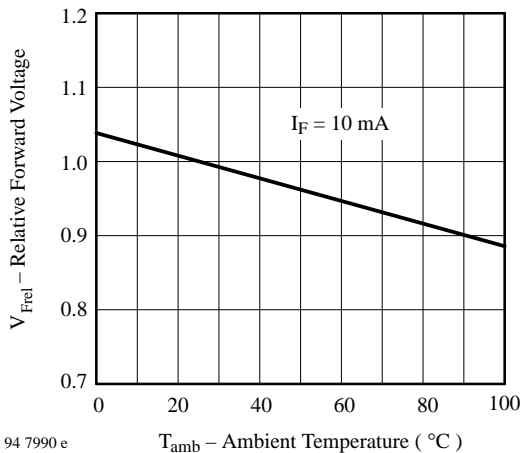


Figure 5 : Relative Forward Voltage vs. Ambient Temperature

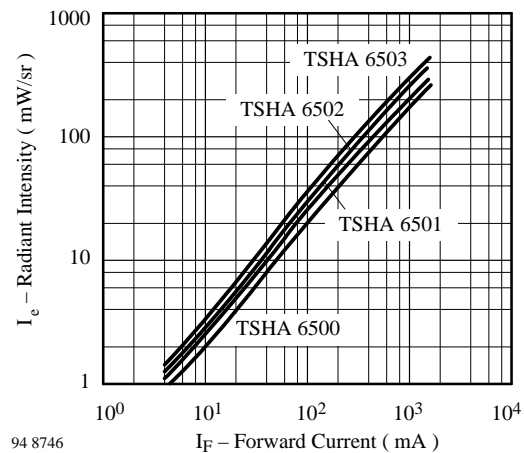


Figure 6 : Radiant Intensity vs. Forward Current

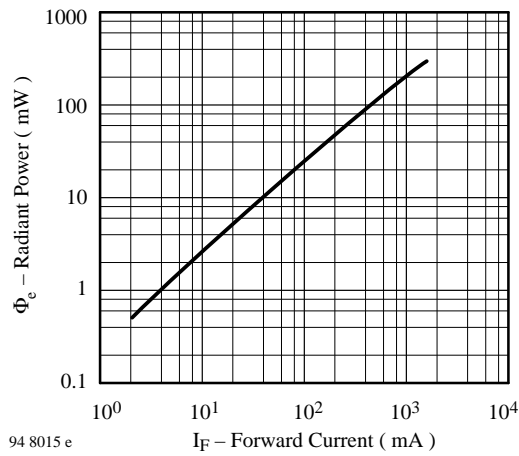


Figure 7 : Radiant Power vs. Forward Current

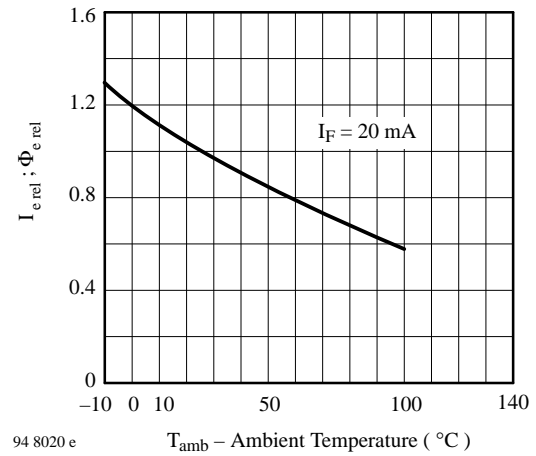


Figure 8 : Rel. Radiant Intensity/Power vs. Ambient Temperature

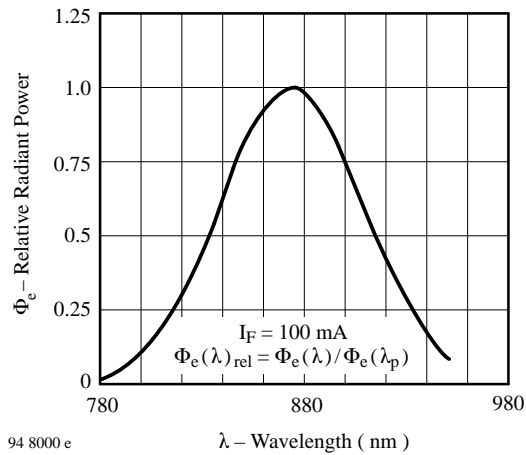


Figure 9 : Relative Radiant Power vs. Wavelength

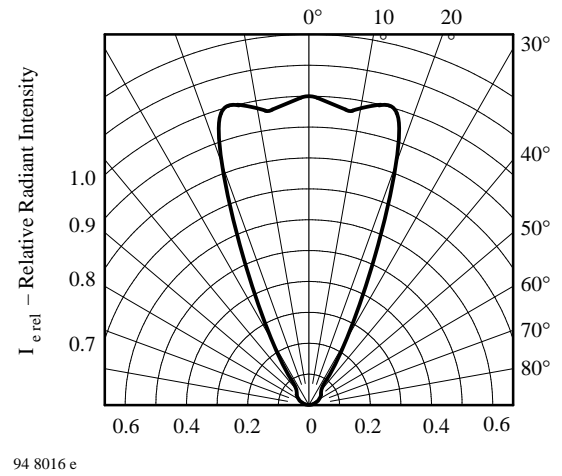
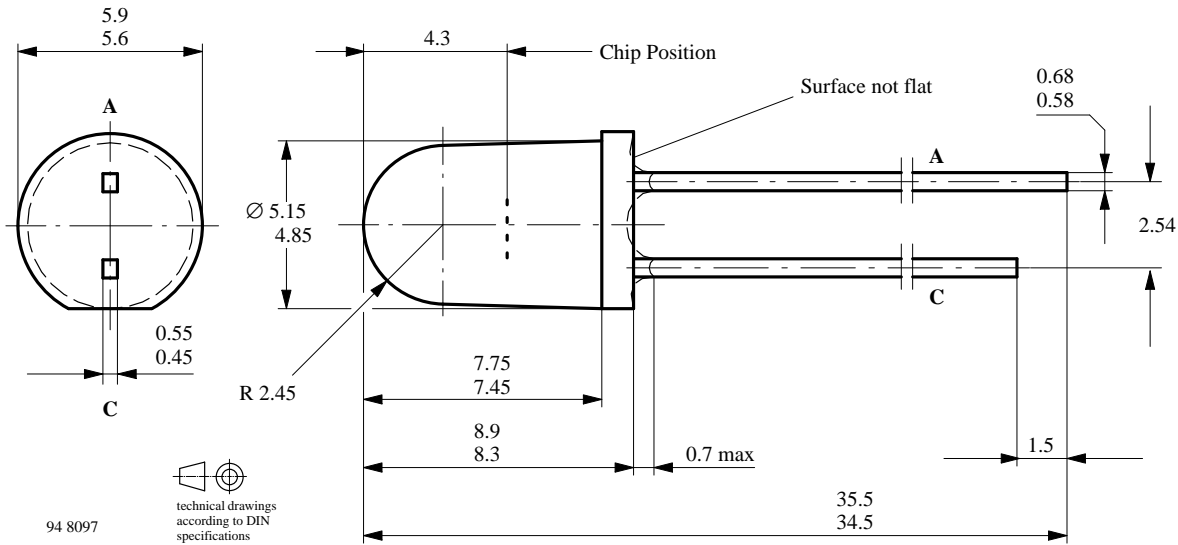


Figure 10 : Relative Radiant Intensity vs. Angular Displacement

## Dimensions in mm



**We reserve the right to make changes to improve technical design without further notice.**

Parameters can vary in different applications. All operating parameters must be validated for each customer application by the customer. Should the buyer use TEMIC products for any unintended or unauthorized application, the buyer shall indemnify TEMIC against all claims, costs, damages, and expenses, arising out of, directly or indirectly, any claim of personal damage, injury or death associated with such unintended or unauthorized use.

TEMIC TELEFUNKEN microelectronic GmbH, P.O.B. 3535, D-74025 Heilbronn, Germany  
 Telephone: 49 (0)7131 67 2831, Fax Number: 49 (0)7131 67 2423